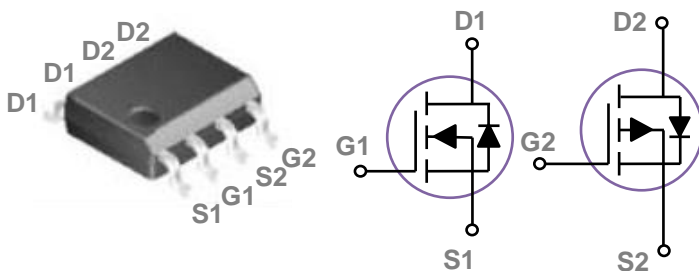


### General Description

These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOP8 Pin Configuration



BVDSS	RDSON	ID
60V	54mΩ	4.5A
-60V	105mΩ	-3.5A

### Features

- Fast switching
- Green Device Available
- Suit for 4.5V Gate Drive Applications

### Applications

- DC Fan
- Motor Drive Applications
- Networking
- Half / Full Bridge Topology

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating		Units
$V_{DS}$	Drain-Source Voltage	60	-60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	4.5	-3.5	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	2.85	-2.21	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	18	-14	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	3.57		W
	Power Dissipation – Derate above $25^\circ\text{C}$	0.028		W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150		$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150		$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	75	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	35	$^\circ\text{C/W}$

**N-CH Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	60	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.05	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =48V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =6A	---	45	54	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A	---	52	63	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	1.8	2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-4.2	---	mV/°C
gfs	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =4A	---	4.2	---	S

**Dynamic and switching Characteristics**

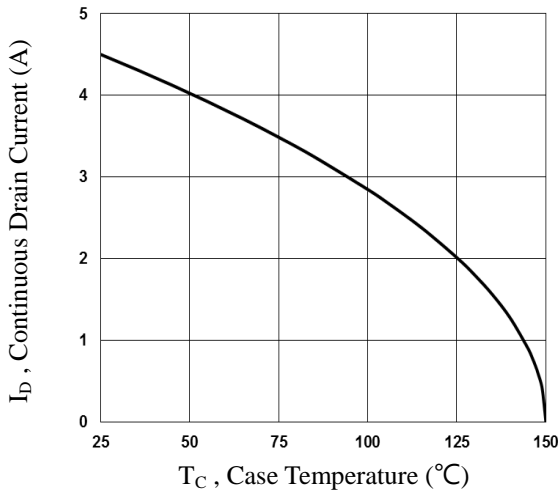
Q <sub>g</sub>	Total Gate Charge <sup>2,3</sup>	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =4A	---	14	21	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2,3</sup>		---	2.9	5	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2,3</sup>		---	2.3	4	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2,3</sup>	V <sub>DD</sub> =30V, V <sub>GS</sub> =10V, R <sub>G</sub> =3.3Ω I <sub>D</sub> =1A	---	3.9	7	ns
T <sub>r</sub>	Rise Time <sup>2,3</sup>		---	12.6	24	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2,3</sup>		---	23.1	44	
T <sub>f</sub>	Fall Time <sup>2,3</sup>		---	6.7	13	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, F=1MHz	---	800	1160	pF
C <sub>oss</sub>	Output Capacitance		---	380	550	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	115	170	
R <sub>g</sub>	Gate resistance		V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	---	1.7	

**Drain-Source Diode Characteristics and Maximum Ratings**

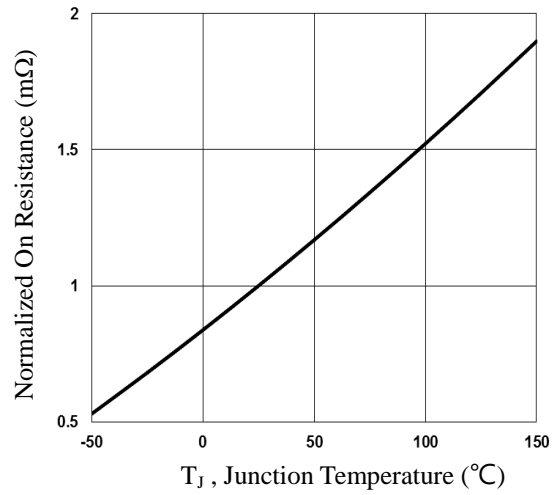
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	4.5	A
I <sub>SM</sub>	Pulsed Source Current		---	---	9	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V

Note :

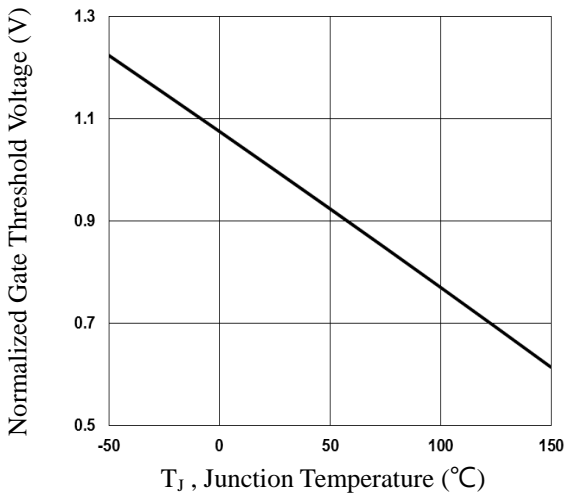
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.



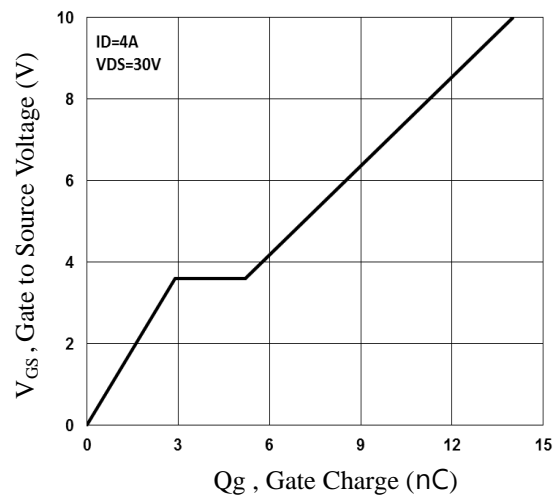
**Fig.1 Continuous Drain Current vs.  $T_c$**



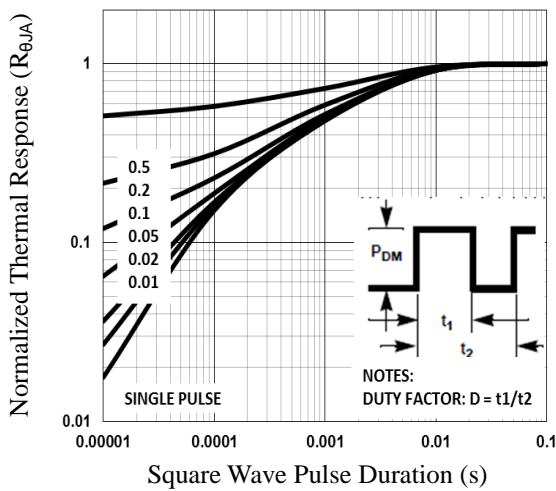
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$**



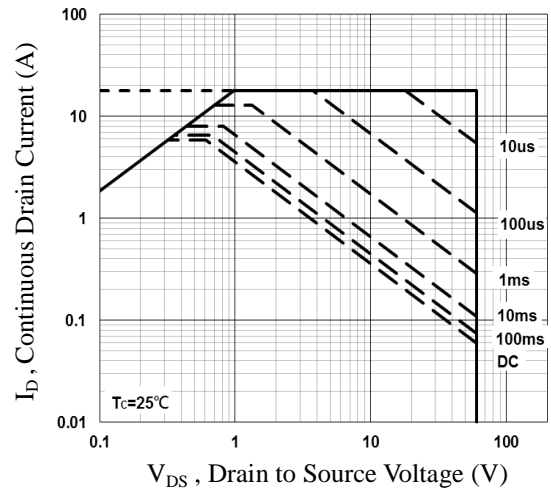
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



**Fig.4 Gate Charge Waveform**



**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

**P-CH Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-60	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =-1mA	---	-0.05	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-60V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	-10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-6A	---	87	105	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3A	---	120	145	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.0	-1.6	-2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	3	---	mV/°C
gfs	Forward Transconductance	V <sub>DS</sub> =-10V, I <sub>D</sub> =-6A	---	5.5	---	S

**Dynamic and switching Characteristics**

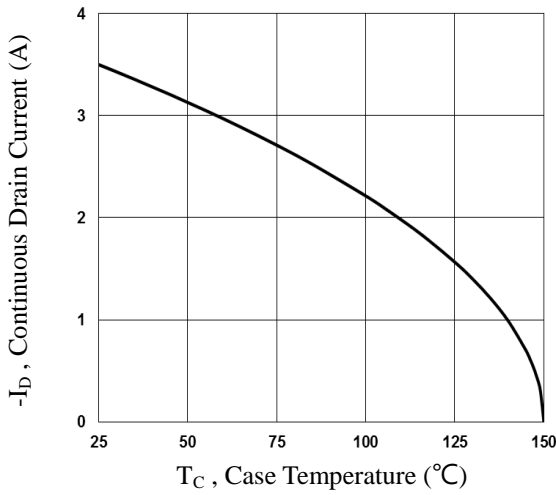
Q <sub>g</sub>	Total Gate Charge <sup>2,3</sup>	V <sub>DS</sub> =-30V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-4A	---	10	15	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2,3</sup>		---	1.6	3.2	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2,3</sup>		---	3	6	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2,3</sup>	V <sub>DD</sub> =-30V, V <sub>GS</sub> =-10V, R <sub>G</sub> =6Ω I <sub>D</sub> =-1A	---	8	16	ns
T <sub>r</sub>	Rise Time <sup>2,3</sup>		---	15.4	30	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2,3</sup>		---	42.8	80	
T <sub>f</sub>	Fall Time <sup>2,3</sup>		---	8.4	16	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V, F=1MHz	---	785	1300	pF
C <sub>oss</sub>	Output Capacitance		---	175	300	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	112	220	

**Drain-Source Diode Characteristics and Maximum Ratings**

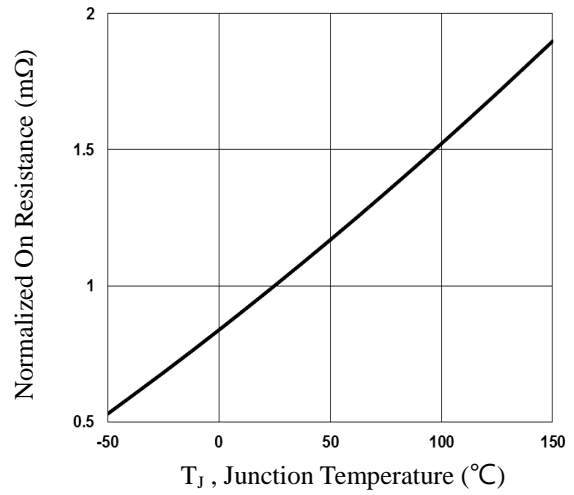
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-3.5	A
I <sub>SM</sub>	Pulsed Source Current		---	---	-7	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C	---	---	-1	V

Note :

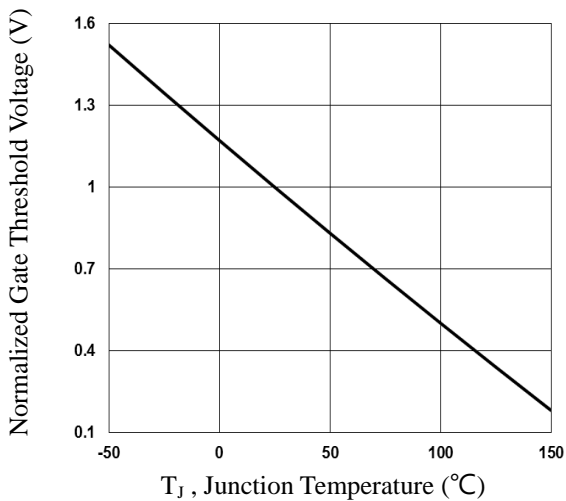
4. Repetitive Rating : Pulsed width limited by maximum junction temperature.
5. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
6. Essentially independent of operating temperature.



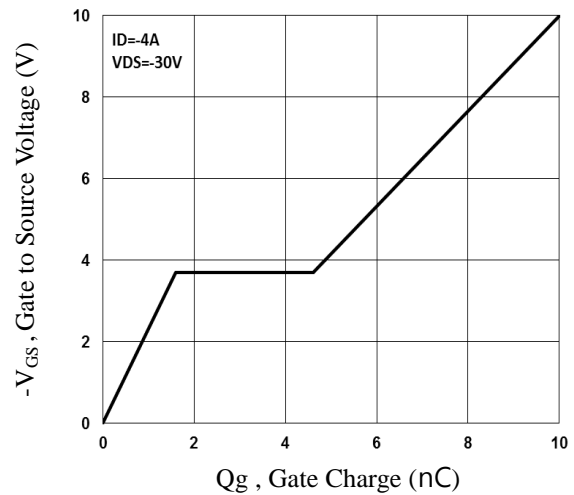
**Fig.7 Continuous Drain Current vs.  $T_C$**



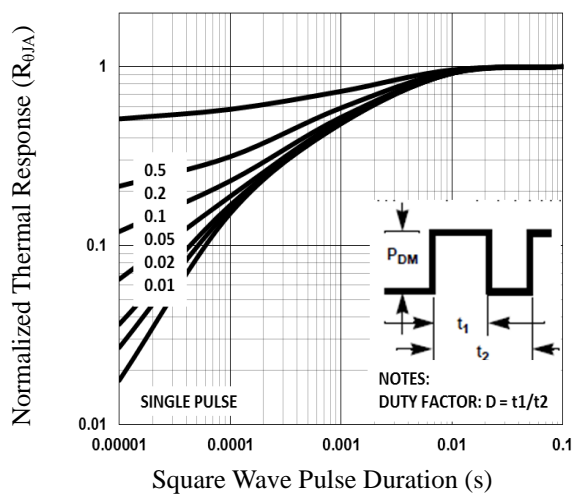
**Fig.8 Normalized  $R_{DS(on)}$  vs.  $T_J$**



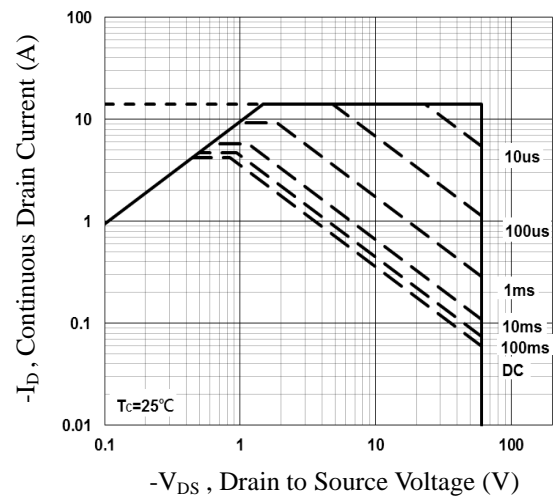
**Fig.9 Normalized  $V_{th}$  vs.  $T_J$**



**Fig.10 Gate Charge Waveform**

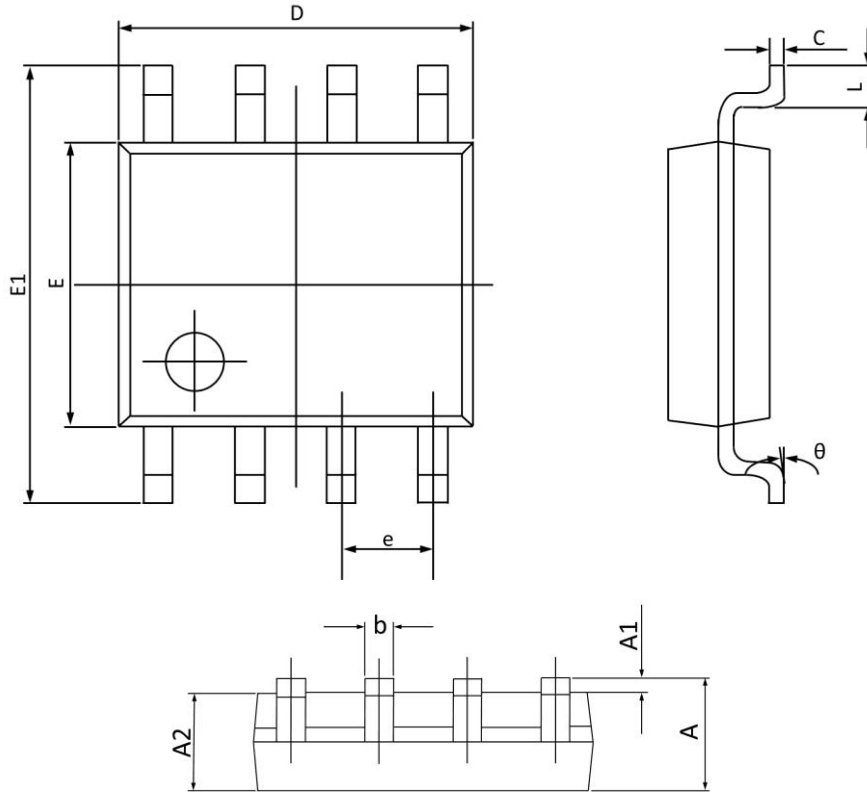


**Fig.11 Normalized Transient Impedance**



**Fig.12 Maximum Safe Operation Area**

## SOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.750	1.350	0.069	0.053
A1	0.250	0.100	0.010	0.004
A2	1.500	1.300	0.059	0.051
b	0.490	0.350	0.019	0.014
C	0.260	0.190	0.010	0.007
D	5.100	4.700	0.201	0.185
E	4.100	3.700	0.161	0.146
E1	6.200	5.800	0.244	0.228
e	1.27BSC		0.05BSC	
L	0.900	0.400	0.035	0.016
$\theta$	8°	0°	8°	0°